

**Fig.1A**

APPLICATION •  
SEMI-CROSSLINKING

**Fig.1B**

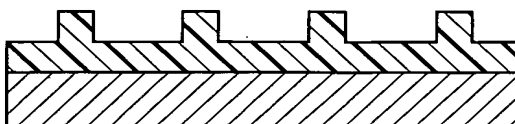
APPLICATION •  
PREBAKE

**Fig.1C** STAMPER  
PREFORM 11

EXPOSURE OR  
SCRIBING •  
DEVELOPMENT

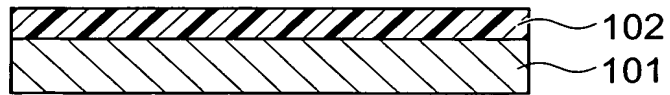
**Fig.1D**

COMPLETE  
CROSSLINKING

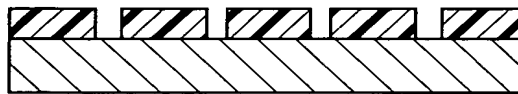
**Fig.1E** STAMPER 21

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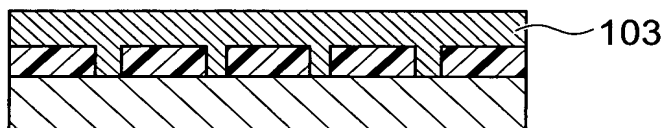
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**Fig.2A**

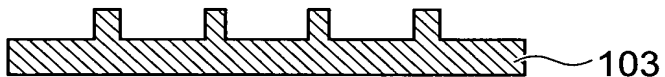
↓ EXPOSURE ·  
DEVELOPMENT

**Fig.2B**

↓ SPUTTERING ·  
Ni ELECTROFORMING

**Fig.2C**

↓ STRIPPING ·  
ASHING

**Fig.2D**

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**Fig.3**